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## Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

### Details

Product Status	Active
Number of LABs/CLBs	6000
Number of Logic Elements/Cells	24000
Total RAM Bits	1032192
Number of I/O	197
Number of Gates	-
Voltage - Supply	1.045V ~ 1.155V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	381-FBGA
Supplier Device Package	381-CABGA (17x17)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe5u-25f-6bg381i">https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe5u-25f-6bg381i</a>

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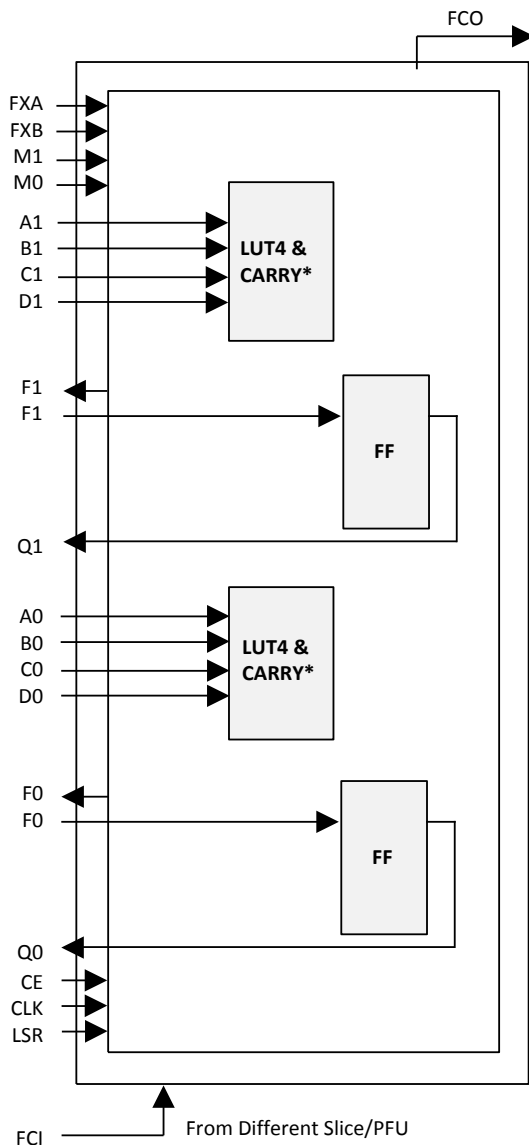
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**Notes:** For Slices 0 and 1, memory control signals are generated from Slice 2 as follows:

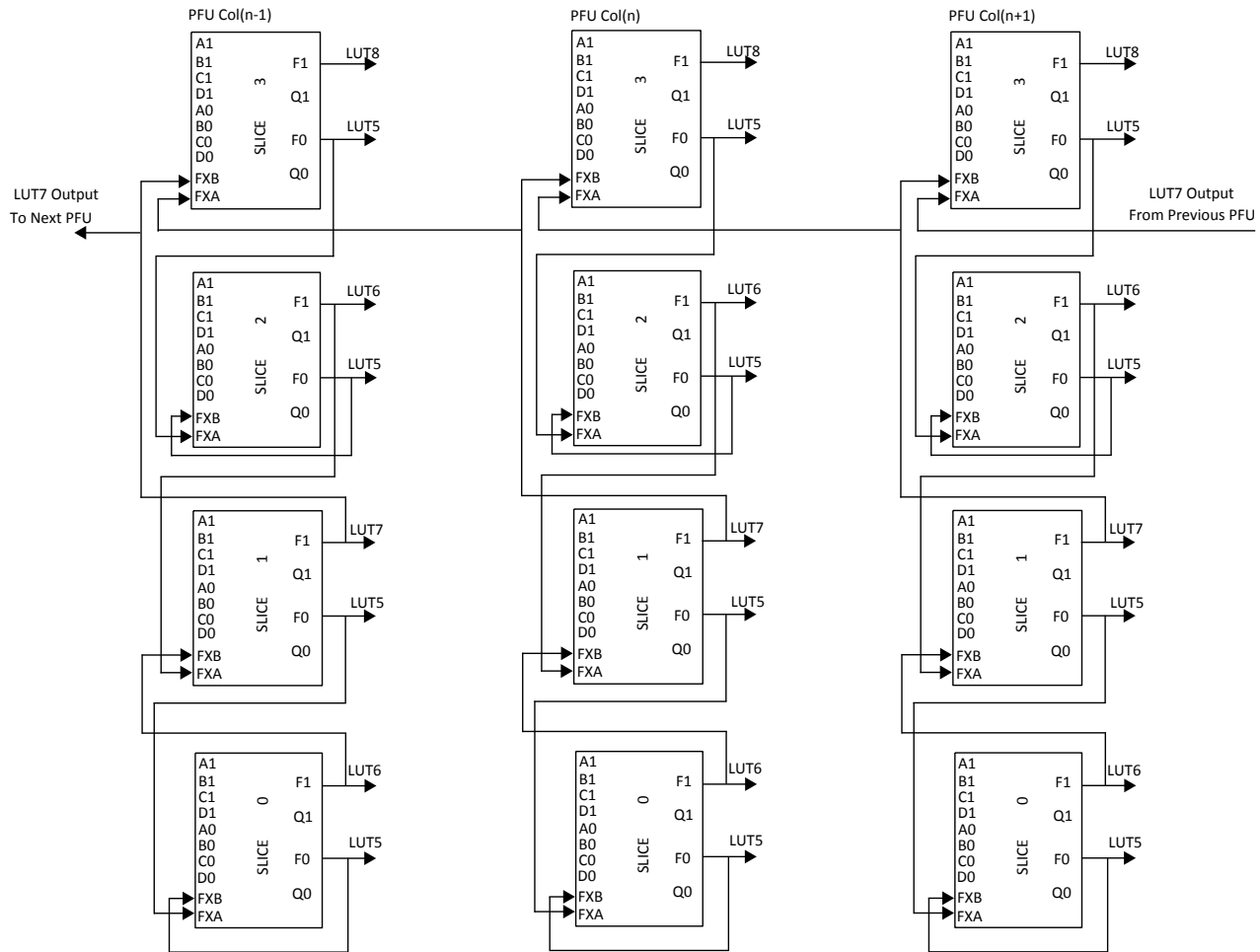
WCK is CLK

WRE is from LSR

DI[3:2] for Slice 1 and DI[1:0] for Slice 0 data from Slice 2

WAD [A:D] is a 4-bit address from slice 2 LUT input

**Figure 2.3. Slice Diagram**



**Figure 2.4. Connectivity Supporting LUT5, LUT6, LUT7, and LUT8**

**Table 2.2. Slice Signal Descriptions**

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCI	Fast Carry-in <sup>1</sup>
Input	Inter-slice signal	FXA	Intermediate signal to generate LUT6, LUT7 and LUT8 <sup>2</sup>
Input	Inter-slice signal	FXB	Intermediate signal to generate LUT6, LUT7 and LUT8 <sup>2</sup>
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register outputs
Output	Inter-PFU signal	FCO	Fast carry chain output <sup>1</sup>

**Notes:**

1. See [Figure 2.3](#) on page 15 for connection details.
2. Requires two adjacent PFUs.

## 2.3. Routing

There are many resources provided in the ECP5/ECP5-5G devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments. The ECP5/ECP5-5G family has an enhanced routing architecture that produces a compact design. The Diamond design software tool suites take the output of the synthesis tool and places and routes the design.

## 2.4. Clocking Structure

ECP5/ECP5-5G clocking structure consists of clock synthesis blocks (sysCLOCK PLL); balanced clock tree networks (PCLK and ECLK trees); and efficient clock logic modules (CLOCK DIVIDER and Dynamic Clock Select (DCS), Dynamic Clock Control (DCC) and DLL). All of these functions are described below.

### 2.4.1. sysCLOCK PLL

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. The devices in the ECP5/ECP5-5G family support two to four full-featured General Purpose PLLs. The sysCLOCK PLLs provide the ability to synthesize clock frequencies. The architecture of the PLL is shown in Figure 2.5. A description of the PLL functionality follows.

CLKI is the reference frequency input to the PLL and its source can come from two different external CLK inputs or from internal routing. A non-glitchless 2-to-1 input multiplexor is provided to dynamically select between two different external reference clock sources. The CLKI input feeds into the input Clock Divider block.

CLKFB is the feedback signal to the PLL which can come from internal feedback path, routing or an external I/O pin. The feedback divider is used to multiply the reference frequency and thus synthesize a higher frequency clock output.

The PLL has four clock outputs CLKOP, CLKOS, CLKOS2 and CLKOS3. Each output has its own output divider, thus allowing the PLL to generate different frequencies for each output. The output dividers can have a value from 1 to 128. The CLKOP, CLKOS, CLKOS2, and CLKOS3 outputs can all be used to drive the primary clock network. Only CLKOP and CLKOS outputs can go to the edge clock network.

The setup and hold times of the device can be improved by programming a phase shift into the CLKOS, CLKOS2, and CLKOS3 output clocks which will advance or delay the output clock with reference to the CLKOP output clock. This phase shift can be either programmed during configuration or can be adjusted dynamically using the PHASESEL, PHASEDIR, PHASESTEP, and PHASELOADREG ports.

The LOCK signal is asserted when the PLL determines it has achieved lock and de-asserted if a loss of lock is detected.

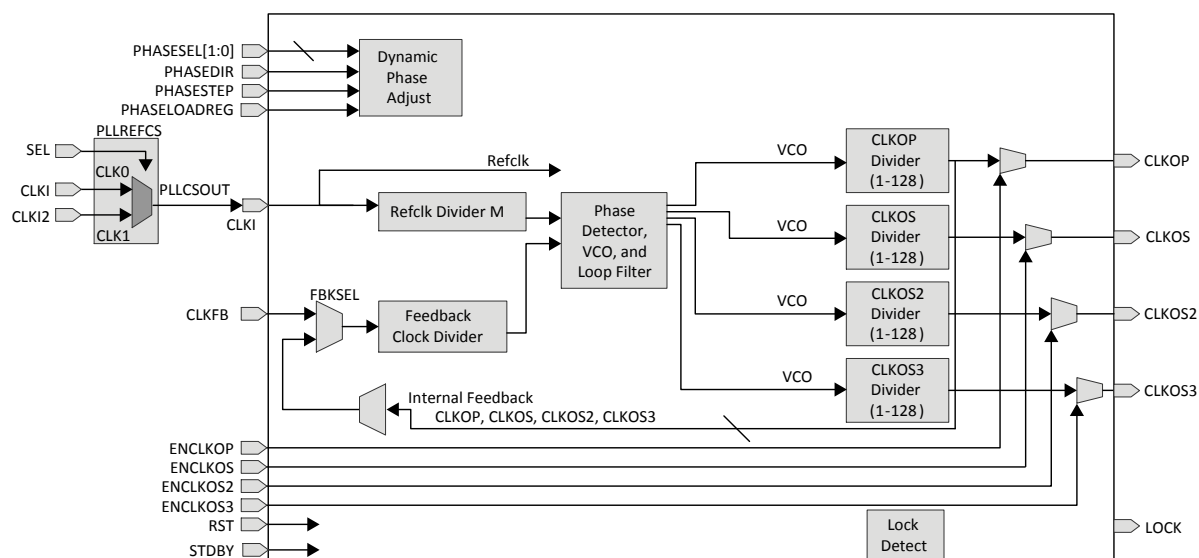


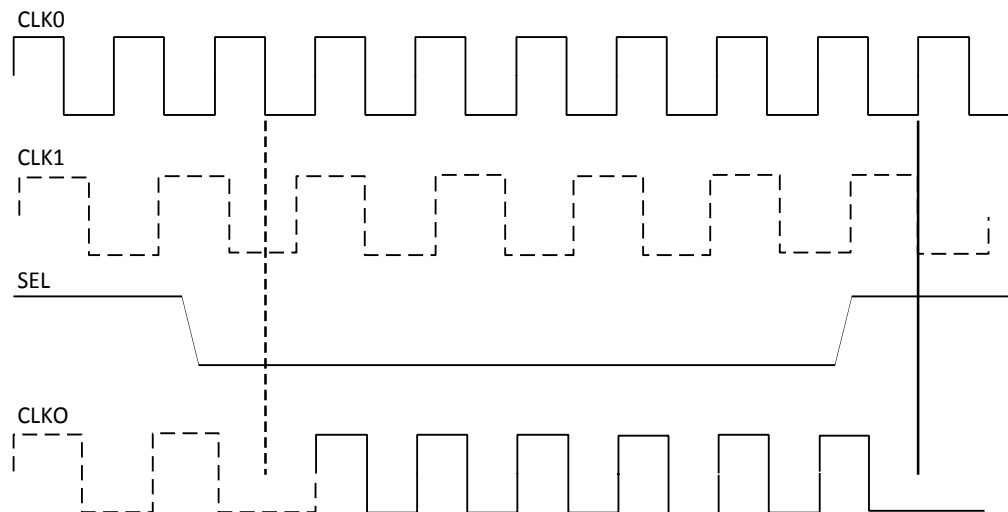
Figure 2.5. General Purpose PLL Diagram

### 2.5.1.2. Dynamic Clock Select

The Dynamic Clock Select (DCS) is a smart multiplexer function available in the primary clock routing. It switches between two independent input clock sources. Depending on the operation modes, it switches between two (2) independent input clock sources either with or without any glitches. This is achieved regardless of when the select signal is toggled. Both input clocks must be running to achieve functioning glitch-less DCS output clock, but it is not required running clocks when used as non-glitch-less normal clock multiplexer.

There are two DCS blocks per device that are fed to all quadrants. The inputs to the DCS block come from all the output of MIDMUXs and Clock from CIB located at the center of the PLC array core. The output of the DCS is connected to one of the inputs of Primary Clock Center MUX.

Figure 2.7 shows the timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information about the DCS, refer to [ECP5 and ECP5-5G sysClock PLL/DLL Design and Usage Guide \(TN1263\)](#).



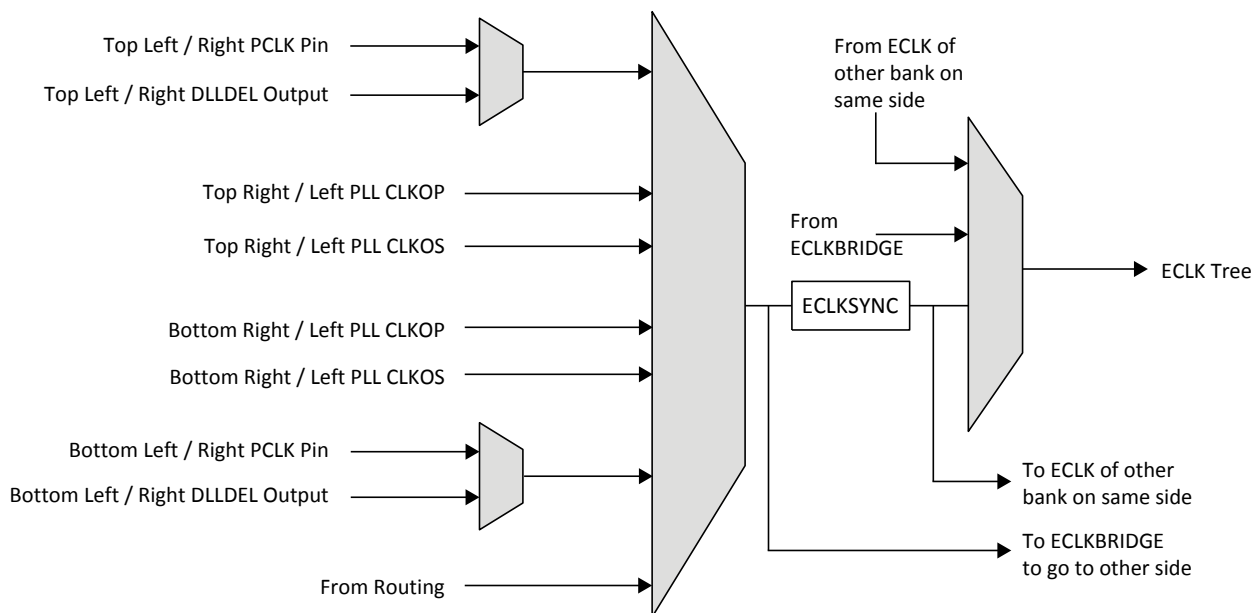
**Figure 2.7. DCS Waveforms**

### 2.5.2. Edge Clock

ECP5/ECP5-5G devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are two ECLK networks per bank IO on the Left and Right sides of the devices.

Each Edge Clock can be sourced from the following:

- Dedicated Clock input pins (PCLK)
- DLLDEL output (Clock delayed by 90°)
- PLL outputs (CLKOP and CLKOS)
- ECLKBRIDGE
- Internal Nodes



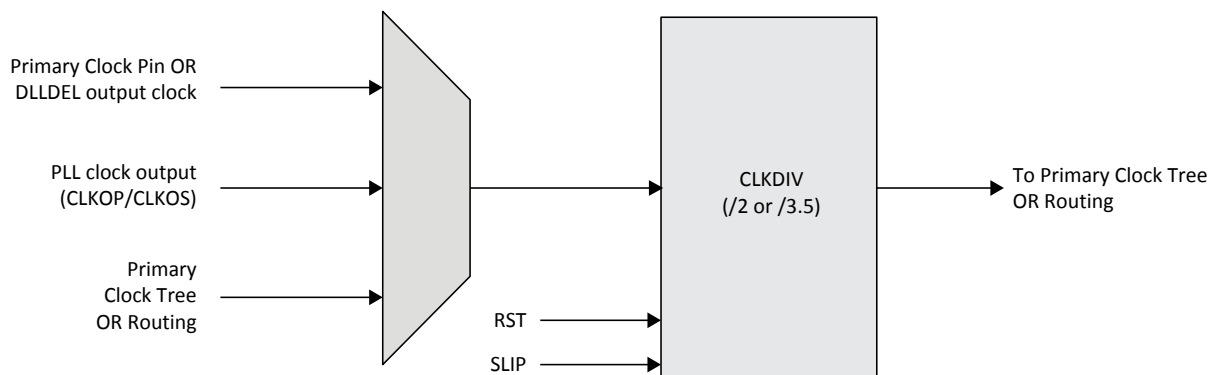
**Figure 2.8. Edge Clock Sources per Bank**

The edge clocks have low injection delay and low skew. They are used for DDR Memory or Generic DDR interfaces. For detailed information on Edge Clock connections, refer to [ECP5 and ECP5-5G sysClock PLL/DLL Design and Usage Guide \(TN1263\)](#).

## 2.6. Clock Dividers

ECP5/ECP5-5G devices have two clock dividers, one on the left side and one on the right side of the device. These are intended to generate a slower-speed system clock from a high-speed edge clock. The block operates in a  $\div 2$ ,  $\div 3.5$  mode and maintains a known phase relationship between the divided down clock and the high-speed clock based on the release of its reset signal.

The clock dividers can be fed from selected PLL outputs, external primary clock pins multiplexed with the DDRDEL Slave Delay or from routing. The clock divider outputs serve as primary clock sources and feed into the clock distribution network. The Reset (RST) control signal resets input and asynchronously forces all outputs to low. The SLIP signal slips the outputs one cycle relative to the input clock. For further information on clock dividers, refer to [ECP5 and ECP5-5G sysClock PLL/DLL Design and Usage Guide \(TN1263\)](#). Figure 2.9 shows the clock divider connections.



**Figure 2.9. ECP5/ECP5-5G Clock Divider Sources**

## 2.11. PIO

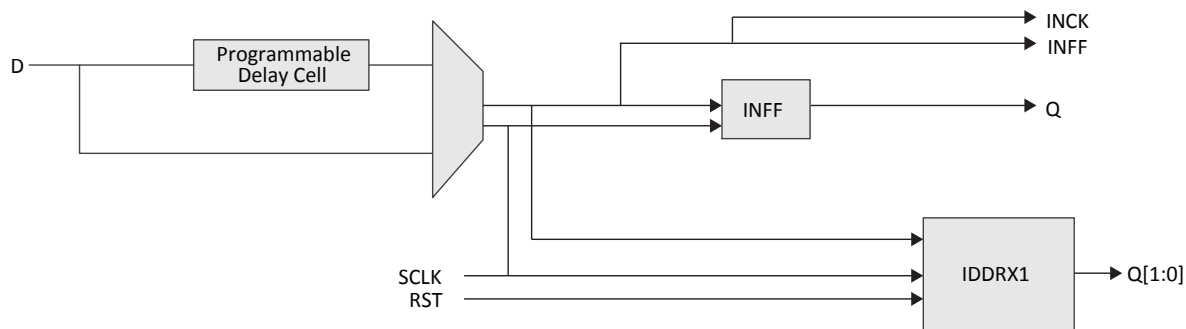
The PIO contains three blocks: an input register block, output register block, and tristate register block. These blocks contain registers for operating in a variety of modes along with the necessary clock and selection logic.

### 2.11.1. Input Register Block

The input register blocks for the PIOs on all edges contain delay elements and registers that can be used to condition high-speed interface signals before they are passed to the device core. In addition, the input register blocks for the PIOs on the left and right edges include built-in FIFO logic to interface to DDR and LPDDR memory.

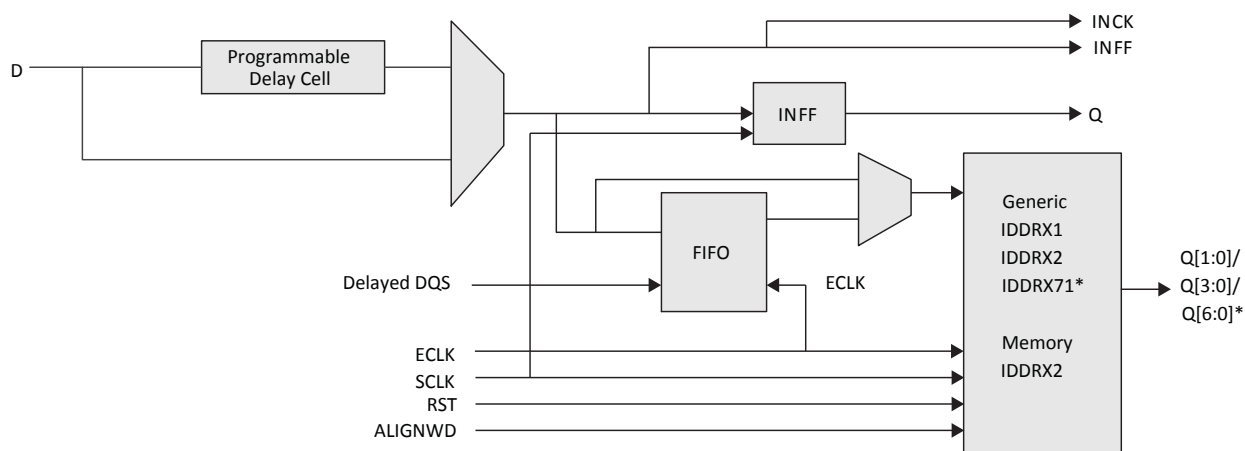
The Input register block on the right and left sides includes gearing logic and registers to implement IDDRX1 and IDDRX2 functions. With two PICs sharing the DDR register path, it can also implement IDDRX71 function used for 7:1 LVDS interfaces. It uses three sets of registers to shift, update, and transfer to implement gearing and the clock domain transfer. The first stage registers samples the high-speed input data by the high-speed edge clock on its rising and falling edges. The second stage registers perform data alignment based on the control signals. The third stage pipeline registers pass the data to the device core synchronized to the low-speed system clock. The top side of the device supports IDDRX1 gearing function. For more information on gearing function, refer to [ECP5 and ECP5-5G High-Speed I/O Interface \(TN1265\)](#).

Figure 2.17 shows the input register block for the PIOs on the top edge.



**Figure 2.17. Input Register Block for PIO on Top Side of the Device**

Figure 2.18 shows the input register block for the PIOs located on the left and right edges.



\*For 7:1 LVDS interface only. It is required to use PIO pair pins (PIOA/B or PIOC/D).

**Figure 2.18. Input Register Block for PIO on Left and Right Side of the Device**



When an error is detected, and the user's error handling software determines the error did not create any risk to the system operation, the SEC tool allows the device to be re-configured in the background to correct the affected bit. This operation allows the user functions to continue to operate without stopping the system function.

Additional SEI tool is also available in the Diamond Software, by creating a frame of data to be programmed into the device in the background with one bit changed, without stopping the user functions on the device. This emulates an SEU situation, allowing the user to test and monitor its error handling software.

For further information on SED support, refer to [LatticeECP3, ECP5 and ECP5-5G Soft Error Detection \(SED\)/Correction \(SEC\) Usage Guide \(TN1184\)](#).

### 2.18.3. On-Chip Oscillator

Every ECP5/ECP5-5G device has an internal CMOS oscillator which is used to derive a Master Clock (MCLK) for configuration. The oscillator and the MCLK run continuously and are available to user logic after configuration is completed. The software default value of the MCLK is nominally 2.4 MHz. [Table 2.16](#) lists all the available MCLK frequencies. When a different Master Clock is selected during the design process, the following sequence takes place:

1. Device powers up with a nominal Master Clock frequency of 2.4 MHz.
2. During configuration, users select a different master clock frequency.
3. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.
4. If the user does not select a master clock frequency, then the configuration bitstream defaults to the MCLK frequency of 2.4 MHz.

This internal oscillator is available to the user by routing it as an input clock to the clock tree. For further information on the use of this oscillator for configuration or user mode, refer to [ECP5 and ECP5-5G sysCONFIG Usage Guide \(TN1260\)](#) and [ECP5 and ECP5-5G sysClock PLL/DLL Design and Usage Guide \(TN1263\)](#).

**Table 2.16. Selectable Master Clock (MCLK) Frequencies during Configuration (Nominal)**

MCLK Frequency (MHz)
2.4
4.8
9.7
19.4
38.8
62

## 2.19. Density Shifting

The ECP5/ECP5-5G family is designed to ensure that different density devices in the same family and in the same package have the same pinout. Furthermore, the architecture ensures a high success rate when performing design migration from lower density devices to higher density devices. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likelihood of success in each case. An example is that some user I/Os may become No Connects in smaller devices in the same package. Refer to the ECP5/ECP5-5G Pin Migration Tables and Diamond software for specific restrictions and limitations.

### 3.13. sysI/O Single-Ended DC Electrical Characteristics

**Table 3.12. Single-Ended DC Characteristics**

Input/Output Standard	V <sub>IL</sub>		V <sub>IH</sub>		V <sub>OL</sub> Max (V)	V <sub>OH</sub> Min (V)	I <sub>OL</sub> <sup>1</sup> (mA)	I <sub>OH</sub> <sup>1</sup> (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVC MOS33	−0.3	0.8	2.0	3.465	0.4	V <sub>CCIO</sub> − 0.4	16, 12, 8, 4	−16, −12, −8, −4
LVC MOS25	−0.3	0.7	1.7	3.465	0.4	V <sub>CCIO</sub> − 0.4	12, 8, 4	−12, −8, −4
LVC MOS18	−0.3	0.35 V <sub>CCIO</sub>	0.65 V <sub>CCIO</sub>	3.465	0.4	V <sub>CCIO</sub> − 0.4	12, 8, 4	−12, −8, −4
LVC MOS15	−0.3	0.35 V <sub>CCIO</sub>	0.65 V <sub>CCIO</sub>	3.465	0.4	V <sub>CCIO</sub> − 0.4	8, 4	−8, −4
LVC MOS12	−0.3	0.35 V <sub>CCIO</sub>	0.65 V <sub>CCIO</sub>	3.465	0.4	V <sub>CCIO</sub> − 0.4	8, 4	−8, −4
LVTTL33	−0.3	0.8	2.0	3.465	0.4	V <sub>CCIO</sub> − 0.4	16, 12, 8, 4	−16, −12, −8, −4
SSTL18_I (DDR2 Memory)	−0.3	V <sub>REF</sub> − 0.125	V <sub>REF</sub> + 0.125	3.465	0.4	V <sub>CCIO</sub> − 0.4	6.7	−6.7
SSTL18_II	−0.3	V <sub>REF</sub> −	V <sub>REF</sub> + 0.125	3.465	0.28	V <sub>CCIO</sub> − 0.28	13.4	−13.4
SSTL15_I (DDR3 Memory)	−0.3	V <sub>REF</sub> − 0.1	V <sub>REF</sub> + 0.1	3.465	0.31	V <sub>CCIO</sub> − 0.31	7.5	−7.5
SSTL15_II (DDR3 Memory)	−0.3	V <sub>REF</sub> − 0.1	V <sub>REF</sub> + 0.1	3.465	0.31	V <sub>CCIO</sub> − 0.31	8.8	−8.8
SSTL135_I (DDR3L Memory)	−0.3	V <sub>REF</sub> − 0.09	V <sub>REF</sub> + 0.09	3.465	0.27	V <sub>CCIO</sub> − 0.27	7	−7
SSTL135_II (DDR3L Memory)	−0.3	V <sub>REF</sub> − 0.09	V <sub>REF</sub> + 0.09	3.465	0.27	V <sub>CCIO</sub> − 0.27	8	−8
MIPI D-PHY (LP) <sup>3</sup>	−0.3	0.55	0.88	3.465	—	—	—	—
HSUL12 (LPDDR2/3 Memory)	−0.3	V <sub>REF</sub> − 0.1	V <sub>REF</sub> + 0.1	3.465	0.3	V <sub>CCIO</sub> − 0.3	4	−4

**Notes:**

1. For electromigration, the average DC current drawn by the I/O pads within a bank of I/Os shall not exceed 10 mA per I/O (All I/Os used in the same V<sub>CCIO</sub>).
2. Not all IO types are supported in all banks. Refer to [ECP5 and ECP5-5G sysIO Usage Guide \(TN1262\)](#) for details.
3. MIPI D-PHY LP input can be implemented by powering VCCIO to 1.5V, and select MIPI LP primitive to meet MIPI Alliance spec on V<sub>IH</sub> and V<sub>IL</sub>. It can also be implemented as LVC MOS12 with VCCIO at 1.2V, which would meet V<sub>IH</sub>/V<sub>IL</sub> spec on LVC MOS12.

### 3.14.4. LVDS25E

The top and bottom sides of ECP5/ECP5-5G devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3.1 is one possible solution for point-to-point signals.

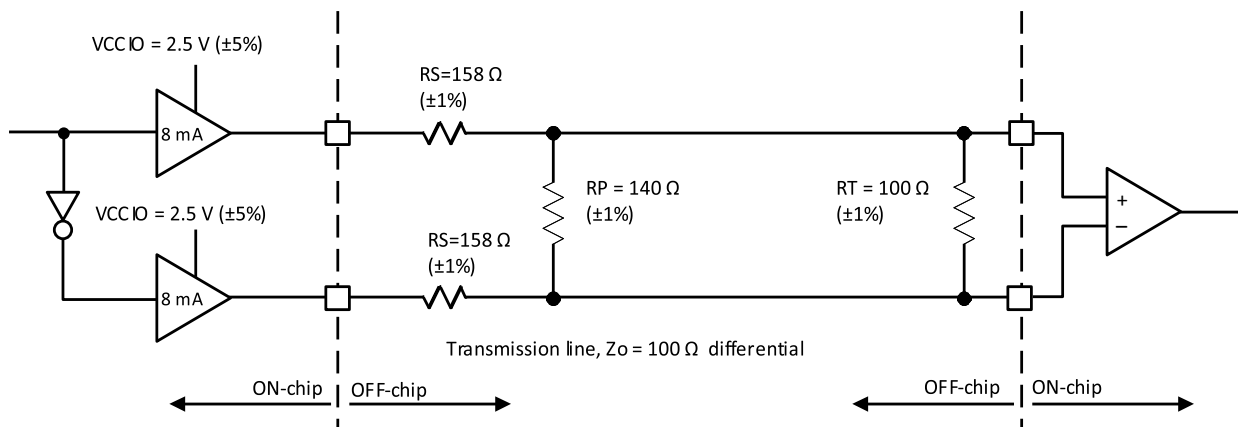


Figure 3.1. LVDS25E Output Termination Example

Table 3.14. LVDS25E DC Conditions

Parameter	Description	Typical	Unit
V <sub>CCIO</sub>	Output Driver Supply (±5%)	2.50	V
Z <sub>OUT</sub>	Driver Impedance	20	Ω
R <sub>S</sub>	Driver Series Resistor (±1%)	158	Ω
R <sub>P</sub>	Driver Parallel Resistor (±1%)	140	Ω
R <sub>T</sub>	Receiver Termination (±1%)	100	Ω
V <sub>OH</sub>	Output High Voltage	1.43	V
V <sub>OL</sub>	Output Low Voltage	1.07	V
V <sub>OD</sub>	Output Differential Voltage	0.35	V
V <sub>CM</sub>	Output Common Mode Voltage	1.25	V
Z <sub>BACK</sub>	Back Impedance	100.5	Ω
I <sub>DC</sub>	DC Output Current	6.03	mA

**Note:** For input buffer, see LVDS Table 3.13 on page 55.

### 3.17. Maximum I/O Buffer Speed

Over recommended operating conditions.

**Table 3.21. ECP5/ECP5-5G Maximum I/O Buffer Speed**

Buffer	Description	Max	Unit
<b>Maximum Input Frequency</b>			
LVDS25	LVDS, $V_{CCIO} = 2.5\text{ V}$	400	MHz
MLVDS25	MLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	400	MHz
BLVDS25	BLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	400	MHz
MIPI D-PHY (HS Mode)	MIPI Video	400	MHz
SLVS	SLVS similar to MIPI	400	MHz
Mini LVDS	Mini LVDS	400	MHz
LVPECL33	LVPECL, Emulated, $V_{CCIO} = 3.3\text{ V}$	400	MHz
SSTL18 (all supported classes)	SSTL_18 class I, II, $V_{CCIO} = 1.8\text{ V}$	400	MHz
SSTL15 (all supported classes)	SSTL_15 class I, II, $V_{CCIO} = 1.5\text{ V}$	400	MHz
SSTL135 (all supported classes)	SSTL_135 class I, II, $V_{CCIO} = 1.35\text{ V}$	400	MHz
HSUL12 (all supported classes)	HSUL_12 class I, II, $V_{CCIO} = 1.2\text{ V}$	400	MHz
LVTTL33	LVTTL, $V_{CCIO} = 3.3\text{ V}$	200	MHz
LVC MOS33	LVC MOS, $V_{CCIO} = 3.3\text{ V}$	200	MHz
LVC MOS25	LVC MOS, $V_{CCIO} = 2.5\text{ V}$	200	MHz
LVC MOS18	LVC MOS, $V_{CCIO} = 1.8\text{ V}$	200	MHz
LVC MOS15	LVC MOS 1.5, $V_{CCIO} = 1.5\text{ V}$	200	MHz
LVC MOS12	LVC MOS 1.2, $V_{CCIO} = 1.2\text{ V}$	200	MHz
<b>Maximum Output Frequency</b>			
LVDS25E	LVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	150	MHz
LVDS25	LVDS, $V_{CCIO} = 2.5\text{ V}$	400	MHz
MLVDS25	MLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	150	MHz
BLVDS25	BLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	150	MHz
LVPECL33	LVPECL, Emulated, $V_{CCIO} = 3.3\text{ V}$	150	MHz
SSTL18 (all supported classes)	SSTL_18 class I, II, $V_{CCIO} = 1.8\text{ V}$	400	MHz
SSTL15 (all supported classes)	SSTL_15 class I, II, $V_{CCIO} = 1.5\text{ V}$	400	MHz
SSTL135 (all supported classes)	SSTL_135 class I, II, $V_{CCIO} = 1.35\text{ V}$	400	MHz
HSUL12 (all supported classes)	HSUL12 class I, II, $V_{CCIO} = 1.2\text{ V}$	400	MHz
LVTTL33	LVTTL, $V_{CCIO} = 3.3\text{ V}$	150	MHz
LVC MOS33 (For all drives)	LVC MOS, 3.3 V	150	MHz
LVC MOS25 (For all drives)	LVC MOS, 2.5 V	150	MHz
LVC MOS18 (For all drives)	LVC MOS, 1.8 V	150	MHz
LVC MOS15 (For all drives)	LVC MOS, 1.5 V	150	MHz
LVC MOS12 (For all drives)	LVC MOS, 1.2 V	150	MHz

**Notes:**

1. These maximum speeds are characterized but not tested on every device.
2. Maximum I/O speed for differential output standards emulated with resistors depends on the layout.
3. LVC MOS timing is measured with the load specified in Switching Test Conditions, Table 3.44 on page 90.
4. All speeds are measured at fast slew.
5. Actual system operation may vary depending on user logic implementation.
6. Maximum data rate equals 2 times the clock rate when utilizing DDR.

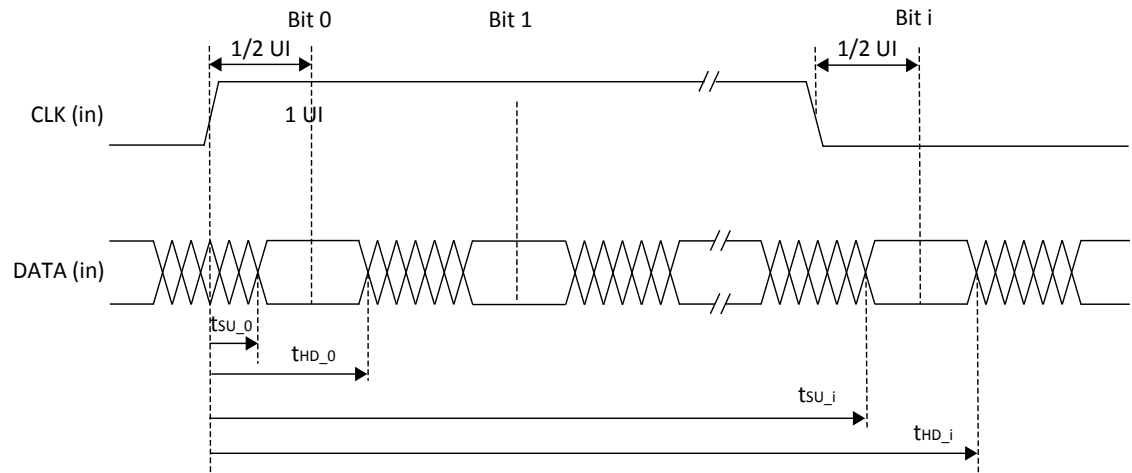


Figure 3.11. Receiver DDRX71\_RX Waveforms

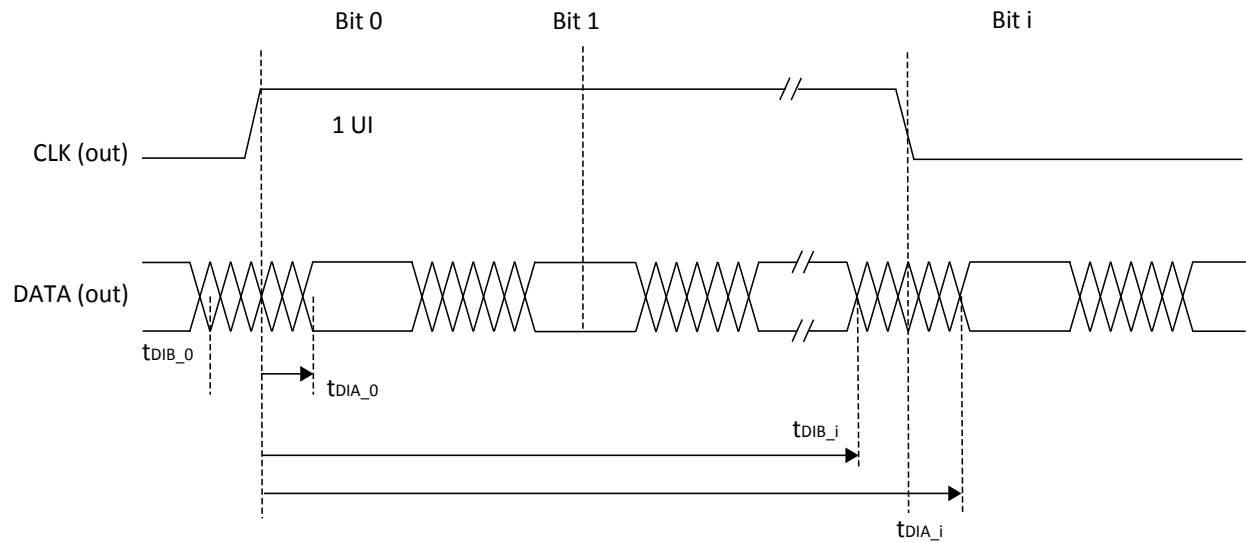
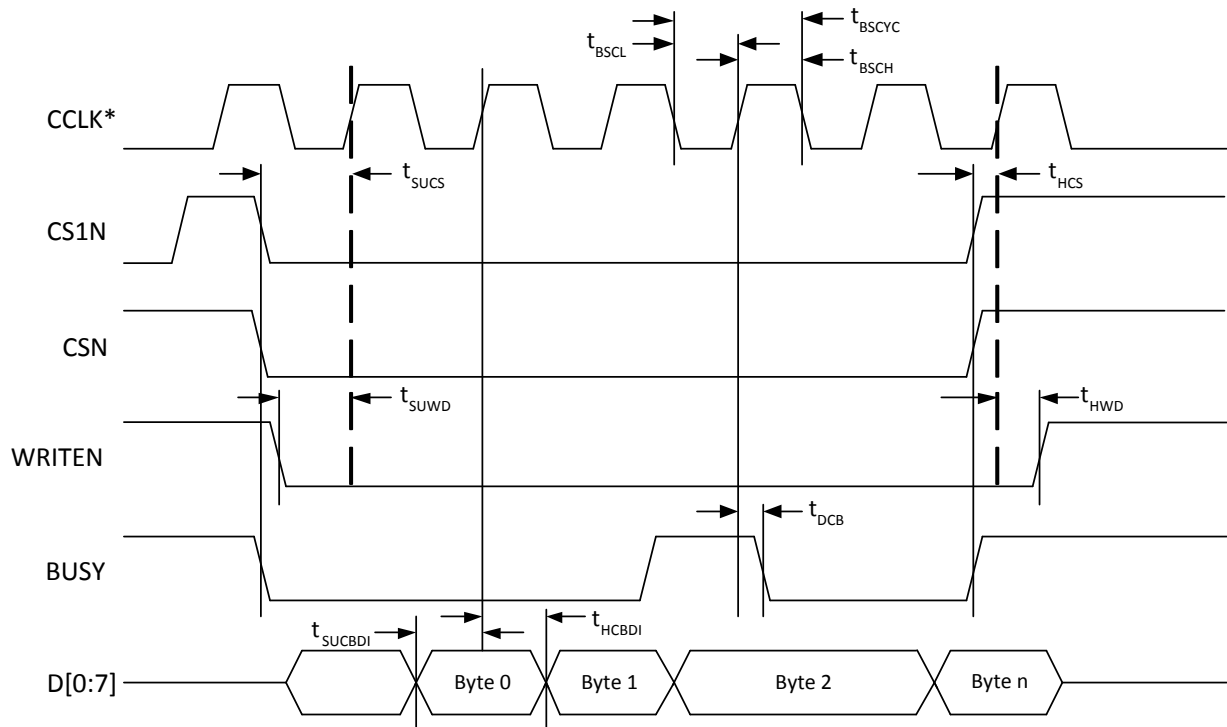
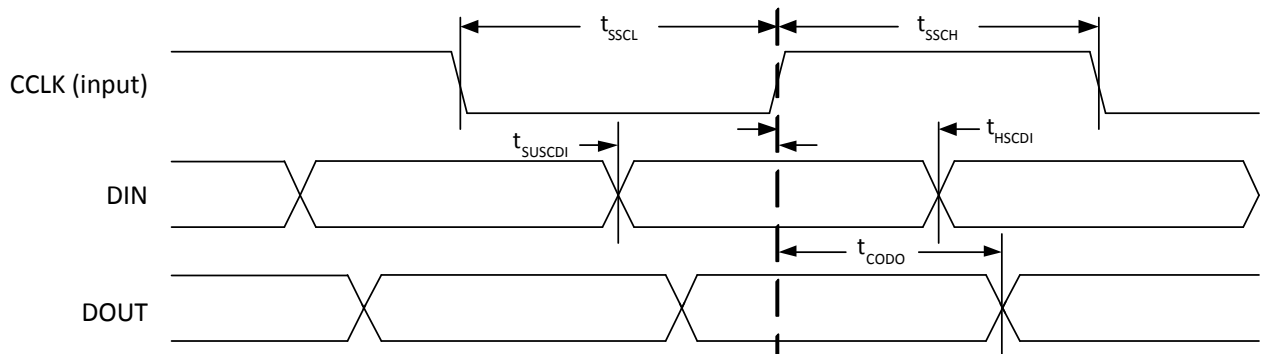


Figure 3.12. Transmitter DDRX71\_TX Waveforms

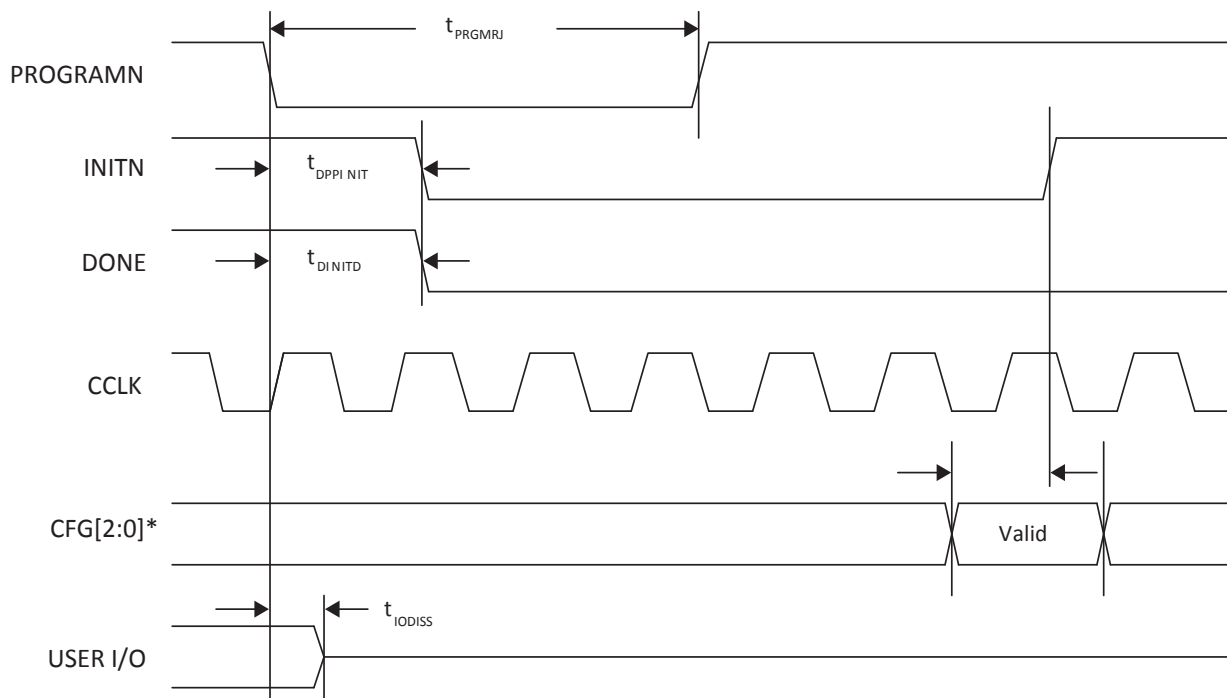


\*In Master Parallel Mode the FPGA provides CCLK (MCLK). In Slave Parallel Mode the external device provides CCLK.

**Figure 3.16. sysCONFIG Parallel Port Write Cycle**

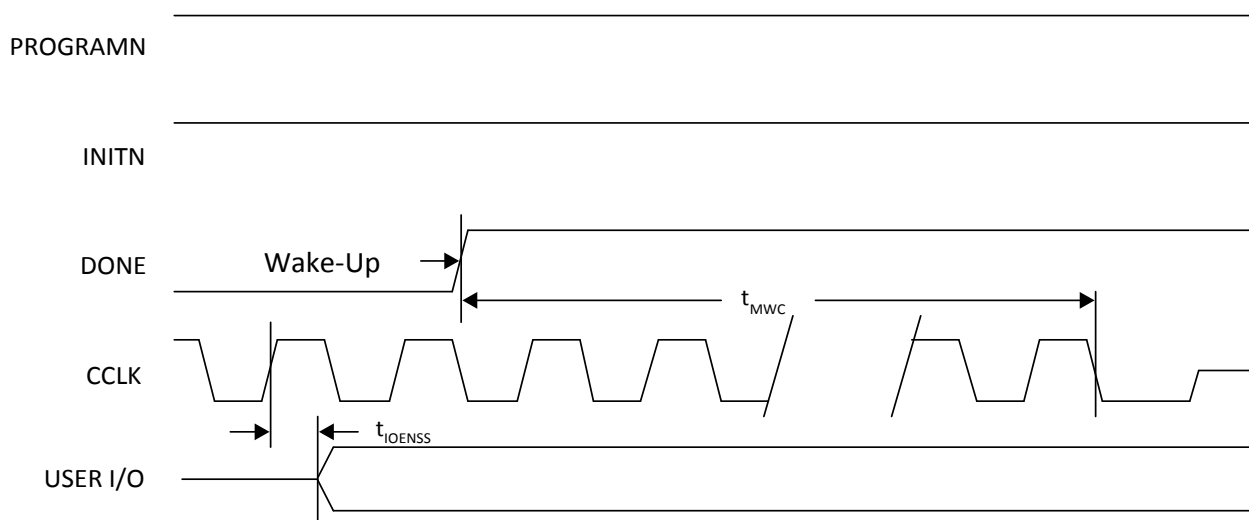


**Figure 3.17. sysCONFIG Slave Serial Port Timing**



\*The CFG pins are normally static (hardwired).

**Figure 3.20. Configuration from PROGRAMN Timing**



**Figure 3.21. Wake-Up Timing**

Signal Name	I/O	Description
<b>Configuration Pads (Used during sysCONFIG) (Continued)</b>		
D1/MISO/IO1	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an input in Master mode, and output in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D2/IO2	I/O	Parallel configuration I/O. Open drain during configuration. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D3/IO3	I/O	Parallel configuration I/O. Open drain during configuration. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D4/IO4	I/O	Parallel configuration I/O. Open drain during configuration. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D5/IO5	I/O	Parallel configuration I/O. Open drain during configuration. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D6/IO6	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an output in Master mode, and input in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D7/IO7	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an output in Master mode, and input in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
<b>SERDES Function</b>		
VCCA <sub>x</sub>	—	SERDES, transmit, receive, PLL and reference clock buffer power supply for SERDES Dual x. All VCCA supply pins must always be powered to the recommended operating voltage range. If no SERDES channels are used, connect VCCA to VCC. VCCA <sub>x</sub> = 1.1 V for ECP5, VCCA <sub>x</sub> = 1.2 V for ECP5-5G.
VCCAUX <sub>Ax</sub>	—	SERDES Aux Power Supply pin for SERDES Dual x. VCCAUX <sub>Ax</sub> = 2.5 V.
HDRX[P/N]_D[dual_num]CH[chan_num]	I	High-speed SERDES inputs, P = Positive, N = Negative, dual_num = [0, 1], chan_num = [0, 1]. These are dedicated SERDES input pins.
HDTX[P/N]_D[dual_num]CH[chan_num]	O	High-speed SERDES outputs, P = Positive, N = Negative, dual_num = [0, 1], chan_num = [0, 1]. These are dedicated SERDES output pins.
REFCLK[P/N]_D[dual_num]	I	SERDES Reference Clock inputs, P = Positive, N = Negative, dual_num = [0, 1]. These are dedicated SERDES input pins.
VCCHRX_D[dual_num]CH[chan_num]	—	SERDES High-Speed Inputs Termination Voltage Supplies, dual_num = [0, 1], chan_num = [0, 1]. These pins should be powered to 1.1 V on ECP5, or 1.2 V on ECP5-5G.
VCCHTX_D[dual_num]CH[chan_num]	—	SERDES High-Speed Outputs Buffer Voltage Supplies, dual_num = [0, 1], chan_num = [0, 1]. These pins should be powered to 1.1 V on ECP5, or 1.2 V on ECP5-5G.

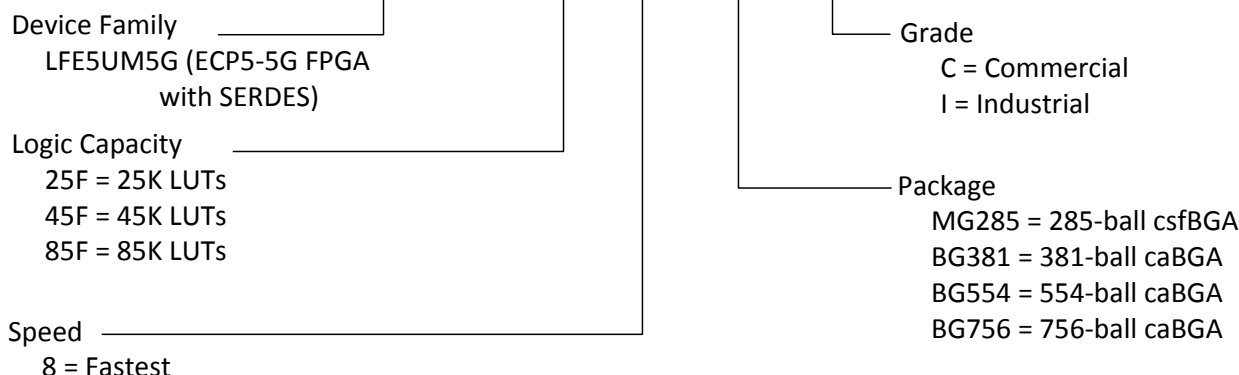
**Notes:**

- When placing switching I/Os around these critical pins that are designed to supply the device with the proper reference or supply voltage, care must be given.
- These pins are dedicated inputs or can be used as general purpose I/O.
- m defines the associated channel in the quad.



Pin Information Summary		LFE5UM/ LFE5UM5G-25		LFE5UM/LFE5UM5G-45			LFE5UM/LFE5UM5G-85			
Pin Type		285 csfBG	381 caBGA	285 csfBGA	381 caBG	554 caBGA	285 csfBGA	381 caBG	554 caBGA	756 caBGA
TAP		4	4	4	4	4	4	4	4	4
Miscellaneous Dedicated Pins		7	7	7	7	7	7	7	7	7
GND		83	59	83	59	113	83	59	113	166
NC		1	8	1	2	33	1	0	17	29
Reserved		0	2	0	2	4	0	2	4	4
SERDES		14	28	14	28	28	14	28	28	28
VCCA (SERDES)	VCCA0	2	2	2	2	6	2	2	6	8
	VCCA1	0	2	0	2	6	0	2	6	9
VCCAUX (SERDES)	VCCAUXA0	2	2	2	2	2	2	2	2	2
	VCCAUXA1	0	2	0	2	2	0	2	2	2
GNDA (SERDES)		26	26	26	26	49	26	26	49	60
Total Balls		285	381	285	381	554	285	381	554	756
High Speed Differential Input / Output Pairs	Bank 0	0	0	0	0	0	0	0	0	0
	Bank 1	0	0	0	0	0	0	0	0	0
	Bank 2	10/8	16/8	10/8	16/8	16/8	10/8	17/9	16/8	24/12
	Bank 3	14/7	16/8	14/7	16/8	24/12	14/7	16/8	24/12	32/16
	Bank 4	0	0	0	0	0	0	0	0	0
	Bank 6	13/6	16/8	13/6	16/8	24/12	13/6	16/8	24/12	32/16
	Bank 7	8/6	16/8	8/6	16/8	16/8	8/6	16/8	16/8	24/12
	Bank 8	0	0	0	0	0	0	0	0	0
Total High Speed Differential I/O Pairs		45/2	64/32	45/27	64/3	80/40	45/27	65/3	80/40	112/5
DQS Groups (> 11 pins in group)	Bank 0	0	0	0	0	0	0	0	0	0
	Bank 1	0	0	0	0	0	0	0	0	0
	Bank 2	1	2	1	2	2	1	2	2	3
	Bank 3	2	2	2	2	3	2	2	3	4
	Bank 4	0	0	0	0	0	0	0	0	0
	Bank 6	2	2	2	2	3	2	2	3	4
	Bank 7	1	2	1	2	2	1	2	2	3
	Bank 8	0	0	0	0	0	0	0	0	0
Total DQS Groups		6	8	6	8	10	6	8	10	14

## LFE5UM5G - XX - X XXXXX X



## 5.2. Ordering Part Numbers

### 5.2.1. Commercial

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5U-12F-6BG256C	-6	Lead free caBGA	256	Commercial	12	No
LFE5U-12F-7BG256C	-7	Lead free caBGA	256	Commercial	12	No
LFE5U-12F-8BG256C	-8	Lead free caBGA	256	Commercial	12	No
LFE5U-12F-6MG285C	-6	Lead free csfBGA	285	Commercial	12	No
LFE5U-12F-7MG285C	-7	Lead free csfBGA	285	Commercial	12	No
LFE5U-12F-8MG285C	-8	Lead free csfBGA	285	Commercial	12	No
LFE5U-12F-6BG381C	-6	Lead free caBGA	381	Commercial	12	No
LFE5U-12F-7BG381C	-7	Lead free caBGA	381	Commercial	12	No
LFE5U-12F-8BG381C	-8	Lead free caBGA	381	Commercial	12	No
LFE5U-25F-6BG256C	-6	Lead free caBGA	256	Commercial	24	No
LFE5U-25F-7BG256C	-7	Lead free caBGA	256	Commercial	24	No
LFE5U-25F-8BG256C	-8	Lead free caBGA	256	Commercial	24	No
LFE5U-25F-6MG285C	-6	Lead free csfBGA	285	Commercial	24	No
LFE5U-25F-7MG285C	-7	Lead free csfBGA	285	Commercial	24	No
LFE5U-25F-8MG285C	-8	Lead free csfBGA	285	Commercial	24	No
LFE5U-25F-6BG381C	-6	Lead free caBGA	381	Commercial	24	No
LFE5U-25F-7BG381C	-7	Lead free caBGA	381	Commercial	24	No
LFE5U-25F-8BG381C	-8	Lead free caBGA	381	Commercial	24	No
LFE5U-45F-6BG256C	-6	Lead free caBGA	256	Commercial	44	No
LFE5U-45F-7BG256C	-7	Lead free caBGA	256	Commercial	44	No
LFE5U-45F-8BG256C	-8	Lead free caBGA	256	Commercial	44	No
LFE5U-45F-6MG285C	-6	Lead free csfBGA	285	Commercial	44	No
LFE5U-45F-7MG285C	-7	Lead free csfBGA	285	Commercial	44	No
LFE5U-45F-8MG285C	-8	Lead free csfBGA	285	Commercial	44	No
LFE5U-45F-6BG381C	-6	Lead free caBGA	381	Commercial	44	No
LFE5U-45F-7BG381C	-7	Lead free caBGA	381	Commercial	44	No
LFE5U-45F-8BG381C	-8	Lead free caBGA	381	Commercial	44	No
LFE5U-45F-6BG554C	-6	Lead free caBGA	554	Commercial	44	No
LFE5U-45F-7BG554C	-7	Lead free caBGA	554	Commercial	44	No

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5U-45F-8BG554C	–8	Lead free caBGA	554	Commercial	44	No
LFE5U-85F-6MG285C	–6	Lead free csfBGA	285	Commercial	84	No
LFE5U-85F-7MG285C	–7	Lead free csfBGA	285	Commercial	84	No
LFE5U-85F-8MG285C	–8	Lead free csfBGA	285	Commercial	84	No
LFE5U-85F-6BG381C	–6	Lead free caBGA	381	Commercial	84	No
LFE5U-85F-7BG381C	–7	Lead free caBGA	381	Commercial	84	No
LFE5U-85F-8BG381C	–8	Lead free caBGA	381	Commercial	84	No
LFE5U-85F-6BG554C	–6	Lead free caBGA	554	Commercial	84	No
LFE5U-85F-7BG554C	–7	Lead free caBGA	554	Commercial	84	No
LFE5U-85F-8BG554C	–8	Lead free caBGA	554	Commercial	84	No
LFE5U-85F-6BG756C	–6	Lead free caBGA	756	Commercial	84	No
LFE5U-85F-7BG756C	–7	Lead free caBGA	756	Commercial	84	No
LFE5U-85F-8BG756C	–8	Lead free caBGA	756	Commercial	84	No
LFE5UM-25F-6MG285C	–6	Lead free csfBGA	285	Commercial	24	Yes
LFE5UM-25F-7MG285C	–7	Lead free csfBGA	285	Commercial	24	Yes
LFE5UM-25F-8MG285C	–8	Lead free csfBGA	285	Commercial	24	Yes
LFE5UM-25F-6BG381C	–6	Lead free caBGA	381	Commercial	24	Yes
LFE5UM-25F-7BG381C	–7	Lead free caBGA	381	Commercial	24	Yes
LFE5UM-25F-8BG381C	–8	Lead free caBGA	381	Commercial	24	Yes
LFE5UM-45F-6MG285C	–6	Lead free csfBGA	285	Commercial	44	Yes
LFE5UM-45F-7MG285C	–7	Lead free csfBGA	285	Commercial	44	Yes
LFE5UM-45F-8MG285C	–8	Lead free csfBGA	285	Commercial	44	Yes
LFE5UM-45F-6BG381C	–6	Lead free caBGA	381	Commercial	44	Yes
LFE5UM-45F-7BG381C	–7	Lead free caBGA	381	Commercial	44	Yes
LFE5UM-45F-8BG381C	–8	Lead free caBGA	381	Commercial	44	Yes
LFE5UM-45F-6BG554C	–6	Lead free caBGA	554	Commercial	44	Yes
LFE5UM-45F-7BG554C	–7	Lead free caBGA	554	Commercial	44	Yes
LFE5UM-45F-8BG554C	–8	Lead free caBGA	554	Commercial	44	Yes
LFE5UM-85F-6MG285C	–6	Lead free csfBGA	285	Commercial	84	Yes
LFE5UM-85F-7MG285C	–7	Lead free csfBGA	285	Commercial	84	Yes
LFE5UM-85F-8MG285C	–8	Lead free csfBGA	285	Commercial	84	Yes
LFE5UM-85F-6BG381C	–6	Lead free caBGA	381	Commercial	84	Yes
LFE5UM-85F-7BG381C	–7	Lead free caBGA	381	Commercial	84	Yes
LFE5UM-85F-8BG381C	–8	Lead free caBGA	381	Commercial	84	Yes
LFE5UM-85F-6BG554C	–6	Lead free caBGA	554	Commercial	84	Yes
LFE5UM-85F-7BG554C	–7	Lead free caBGA	554	Commercial	84	Yes
LFE5UM-85F-8BG554C	–8	Lead free caBGA	554	Commercial	84	Yes
LFE5UM-85F-6BG756C	–6	Lead free caBGA	756	Commercial	84	Yes
LFE5UM-85F-7BG756C	–7	Lead free caBGA	756	Commercial	84	Yes
LFE5UM-85F-8BG756C	–8	Lead free caBGA	756	Commercial	84	Yes
LFE5UM5G-25F-8MG285C	–8	Lead free csfBGA	285	Commercial	24	Yes
LFE5UM5G-25F-8BG381C	–8	Lead free caBGA	381	Commercial	24	Yes
LFE5UM5G-45F-8MG285C	–8	Lead free csfBGA	285	Commercial	44	Yes
LFE5UM5G-45F-8BG381C	–8	Lead free caBGA	381	Commercial	44	Yes
LFE5UM5G-45F-8BG554C	–8	Lead free caBGA	554	Commercial	44	Yes
LFE5UM5G-85F-8MG285C	–8	Lead free csfBGA	285	Commercial	84	Yes

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5UM5G-85F-8BG381C	–8	Lead free caBGA	381	Commercial	84	Yes
LFE5UM5G-85F-8BG554C	–8	Lead free caBGA	554	Commercial	84	Yes
LFE5UM5G-85F-8BG756C	–8	Lead free caBGA	756	Commercial	84	Yes

## 5.2.2. Industrial

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5U-12F-6BG256I	–6	Lead free caBGA	256	Industrial	12	No
LFE5U-12F-7BG256I	–7	Lead free caBGA	256	Industrial	12	No
LFE5U-12F-8BG256I	–8	Lead free caBGA	256	Industrial	12	No
LFE5U-12F-6MG285I	–6	Lead free csfBGA	285	Industrial	12	No
LFE5U-12F-7MG285I	–7	Lead free csfBGA	285	Industrial	12	No
LFE5U-12F-8MG285I	–8	Lead free csfBGA	285	Industrial	12	No
LFE5U-12F-6BG381I	–6	Lead free caBGA	381	Industrial	12	No
LFE5U-12F-7BG381I	–7	Lead free caBGA	381	Industrial	12	No
LFE5U-12F-8BG381I	–8	Lead free caBGA	381	Industrial	12	No
LFE5U-25F-6BG256I	–6	Lead free caBGA	256	Industrial	24	No
LFE5U-25F-7BG256I	–7	Lead free caBGA	256	Industrial	24	No
LFE5U-25F-8BG256I	–8	Lead free caBGA	256	Industrial	24	No
LFE5U-25F-6MG285I	–6	Lead free csfBGA	285	Industrial	24	No
LFE5U-25F-7MG285I	–7	Lead free csfBGA	285	Industrial	24	No
LFE5U-25F-8MG285I	–8	Lead free csfBGA	285	Industrial	24	No
LFE5U-25F-6BG381I	–6	Lead free caBGA	381	Industrial	24	No
LFE5U-25F-7BG381I	–7	Lead free caBGA	381	Industrial	24	No
LFE5U-25F-8BG381I	–8	Lead free caBGA	381	Industrial	24	No
LFE5U-45F-6BG256I	–6	Lead free caBGA	256	Industrial	44	No
LFE5U-45F-7BG256I	–7	Lead free caBGA	256	Industrial	44	No
LFE5U-45F-8BG256I	–8	Lead free caBGA	256	Industrial	44	No
LFE5U-45F-6MG285I	–6	Lead free csfBGA	285	Industrial	44	No
LFE5U-45F-7MG285I	–7	Lead free csfBGA	285	Industrial	44	No
LFE5U-45F-8MG285I	–8	Lead free csfBGA	285	Industrial	44	No
LFE5U-45F-6BG381I	–6	Lead free caBGA	381	Industrial	44	No
LFE5U-45F-7BG381I	–7	Lead free caBGA	381	Industrial	44	No
LFE5U-45F-8BG381I	–8	Lead free caBGA	381	Industrial	44	No
LFE5U-45F-6BG554I	–6	Lead free caBGA	554	Industrial	44	No
LFE5U-45F-7BG554I	–7	Lead free caBGA	554	Industrial	44	No
LFE5U-45F-8BG554I	–8	Lead free caBGA	554	Industrial	44	No
LFE5U-85F-6MG285I	–6	Lead free csfBGA	285	Industrial	84	No
LFE5U-85F-7MG285I	–7	Lead free csfBGA	285	Industrial	84	No
LFE5U-85F-8MG285I	–8	Lead free csfBGA	285	Industrial	84	No
LFE5U-85F-6BG381I	–6	Lead free caBGA	381	Industrial	84	No
LFE5U-85F-7BG381I	–7	Lead free caBGA	381	Industrial	84	No
LFE5U-85F-8BG381I	–8	Lead free caBGA	381	Industrial	84	No
LFE5U-85F-6BG554I	–6	Lead free caBGA	554	Industrial	84	No
LFE5U-85F-7BG554I	–7	Lead free caBGA	554	Industrial	84	No
LFE5U-85F-8BG554I	–8	Lead free caBGA	554	Industrial	84	No

(Continued)

Date	Version	Section	Change Summary
November 2015	1.5	All	Added ECP5-5G device family.
			Changed document title to ECP5 and ECP5-5G Family Data Sheet.
	1.4	General Description	Updated Features section. Added support for eDP in RDR and HDR.
		Architecture	Updated Overview section. Revised Figure 2.1. Simplified Block Diagram, LFE5UM/LFE5UM5G-85 Device (Top Level). Modified Flexible sysIO description and Note.
			Updated SERDES and Physical Coding Sublayer section. <ul style="list-style-type: none"> <li>Changed E.24.V in CPRI protocol to E.24.LV.</li> <li>Removed “1.1 V” from paragraph on unused Dual.</li> </ul>
		DC and Switching Characteristics	Updated Hot Socketing Requirements section. Revised V <sub>CCHTX</sub> in table notes 1 and 3. Indicated V <sub>CCHTX</sub> in table note 4.
			Updated SERDES High-Speed Data Transmitter section. Revised V <sub>CCHTX</sub> in table note 1.
		Ordering Information	Updated ECP5/ECP5-5G Part Number Description section. Changed “LFE5 FPGA” under Device Family to “ECP5 FPGA”.
August 2015	1.3	General Description	Updated Features section. <ul style="list-style-type: none"> <li>Removed SMPTE3G under Embedded SERDES.</li> <li>Added Single Event Upset (SEU) Mitigation Support.</li> </ul> Removed SMPTE protocol in fifth paragraph.
		Architecture	General update.
		DC and Switching Characteristics	General update.
		Pinout Information	Updated Signal Descriptions section. Revised the descriptions of the following signals: <ul style="list-style-type: none"> <li>P[L/R] [Group Number]_[A/B/C/D]</li> <li>P[T/B][Group Number]_[A/B]</li> <li>D4/IO4 (Previously named D4/MOSI2/IO4)</li> <li>D5/IO5 (Previously named D5/MISO/IO5)</li> <li>VCCHRX_D[dual_num]CH[chan_num]</li> <li>VCCHTX_D[dual_num]CH[chan_num]</li> </ul>
		Supplemental Information	Added TN1184 reference.